

# ALPHA<sup>®</sup> HiTech CU31-2030

**Reworkable Underfill Epoxy** 

### DESCRIPTION

**ALPHA HiTech CU31-2030** is a one-component capillary underfill designed for the protection of assembled chip packages on printed circuit boards. It is a low viscosity underfill which enables fast and efficient flow properties. In addition, it has a high Tg and low modulus which results to excellent reliability performance. **ALPHA HiTech CU31-2030** suitable for assembling BGA, CSP and Flip Chip devices.

## READ ENTIRE TECHNICAL DATA SHEET BEFORE USING THIS PRODUCT

#### FEATURES AND BENEFITS

The balanced set of features and benefits for this material are:

- Low Viscosity
- High Glass Transition Temperature (Tg)
- Low Modulus
- Excellent Reliability performance
- Room temperature flow capability
- Reworkable at a temperature above 300 °C
- Halogen-Free
- Complies with RoHS Directive 2015/863/EU





## **APPLICATION GUIDELINES**

Storage	Thawing	Application	Curing
<ol> <li>Freeze at ≤ -20 °C to guarantee product stability.</li> <li>Upright Position, tip facing bottom</li> </ol>	<ol> <li>Remove the syringe from the freezer.</li> <li>Set aside at room temperature for 2 hours.</li> <li>Do not open the cap before the product is sufficiently thawed.</li> </ol>	the freezer. aside at room berature for 2 hours. not open the cap re the product is ciently thawed. luct should not be izen after thawed. revent amination of unused uct, do not return material to its	For full property development, cure at the following conditions in a convection oven. • 120 °C for ≥ 20 minutes • 130 °C for ≥ 10 minutes • 150 °C for ≥ 7.5 minutes
<u>vouit</u>	<ol> <li>Product should not be refrozen after thawed.</li> </ol>		
	<ol> <li>To prevent contamination of unused product, do not return any material to its original container.</li> </ol>		

## **TECHNICAL DATA**

Category	Specification			
Typical Uncured Material Properties				
Appearance	Black			
Viscosity (RVT Brookfield Spindle #3, 20 rpm @ 25 °C, cP)	*200 to 1,000			
Filler Content (SiO2), %	10			
Average Filler Size, μm	0.7			
Maximum Filler Size, μm	10			
Specific Gravity	1.1 to 1.3			
Pot Life @ 25 °C, days	3			
Shelf Life @ ≤ -20 °C, months	6			
Available Packaging	10cc, 30cc syringes			

\*Note: Values are tentative until specification limits have been established and finalized.





Category	Specification			
Typical Cured Materials Properties				
Glass Transition (Tg), °C via TMA	168 ± 5			
CTE (α <sub>1</sub> ), <tg, ppm<="" td=""><td>56 ± 10</td></tg,>	56 ± 10			
CTE (α₂), >Tg, ppm	176 ± 20			
Hardness (Shore D)	80 to 90			
Modulus, Mpa (via DMA @ -40 to 250 °C)	2,787			
Linear Shrinkage, %	0.60			
Volume Shrinkage, %	2.83			
Coefficient of Thermal Conductivity, W/mK	0.80			
Halogen, ppm (per 3rd Party Lab testing)	Br: Not Detected			
Thalogen, ppin (per Sid Party Lab testing)	CI: 90			
Extractable Ionic Content - Anion, ppm	CI <sup>-</sup> : 0.33			
Extractable Ionic Content - Cation, ppm	Not Detected			
Reworkable	>300 °C			
	25 °C for 24 hrs: 0.33			
Water Absorption, %	100 °C for 2 hrs: 0.41			
	ALPHA CVP-390: Pass			
DSC Compatibility Test with Flux Desider	ALPHA OM-340: Pass			
DSC Compatibility Test with Flux Residue	ALPHA OM-353: Pass			
	ALPHA OM-358: Pass			





Category	Typical Values			
Typical Cured Material Properties				
	ALPHA HiTech CU31-2030			
	ALPHA HiTech CU31-2030 +			
	ALPHA CVP-390: Pass			
SIR per IPC J-STD-0004B	ALPHA HiTech CU31-2030 +			
TM-650 Method 2.6.3.7 (40 °C, 90 %RH, 12 V bias)	ALPHA OM-340: Pass			
	ALPHA HiTech CU31-2030 +			
	ALPHA OM-353: Pass			
	ALPHA HiTech CU31-2030 +			
	ALPHA OM-358: Pass			
Thermal Shock (air to Air) @ -40 to 125 °C / Dwell 30 min / cycle (Alloy: SAC305)	Pass up to 3,000 Cycles			
Volume Resistivity, Ω.cm (ASTM D257)	4.3 x 10 <sup>16</sup>			
Surface Resistivity, $\Omega/cm^2$ (ASTM D257)	5.4 x 10 <sup>16</sup>			
Dielectric Breakdown Strength, kV/mm (ASTM D149)	20			
Dielectric Breakdown Voltage, kV (ASTM D149)	61			
Dielectric Constant	1 KHz: 4.67			
(Low Frequency - 1KHz & 1MHz: ASTM D150)	1 MHz: 4.28			
Dissipation Constant	1 KHz: 0.0022			
(Low Frequency - 1KHz & 1MHz: ASTM D150)	1 MHz: 0.0052			





#### **SAFETY & WARNING**

It is recommended that the company/operator read and review the Safety Data Sheets for the appropriate health and safety warnings before use. **Safety Data Sheets are available at MacdermidAlpha.com/assembly-solutions/knowledge-base.** 

#### **CONTACT INFORMATION**

#### To confirm this document is the most recent version, please contact Assembly@MacDermidAlpha.com

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Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE . Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 020, Mexico 01800 002 1400 and (55) 5559 1588

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